



SPADIC v0.3 and v1.0

Self-triggered **P**ulse **A**mplification and **D**igitization as**IC**



Tim Armbruster

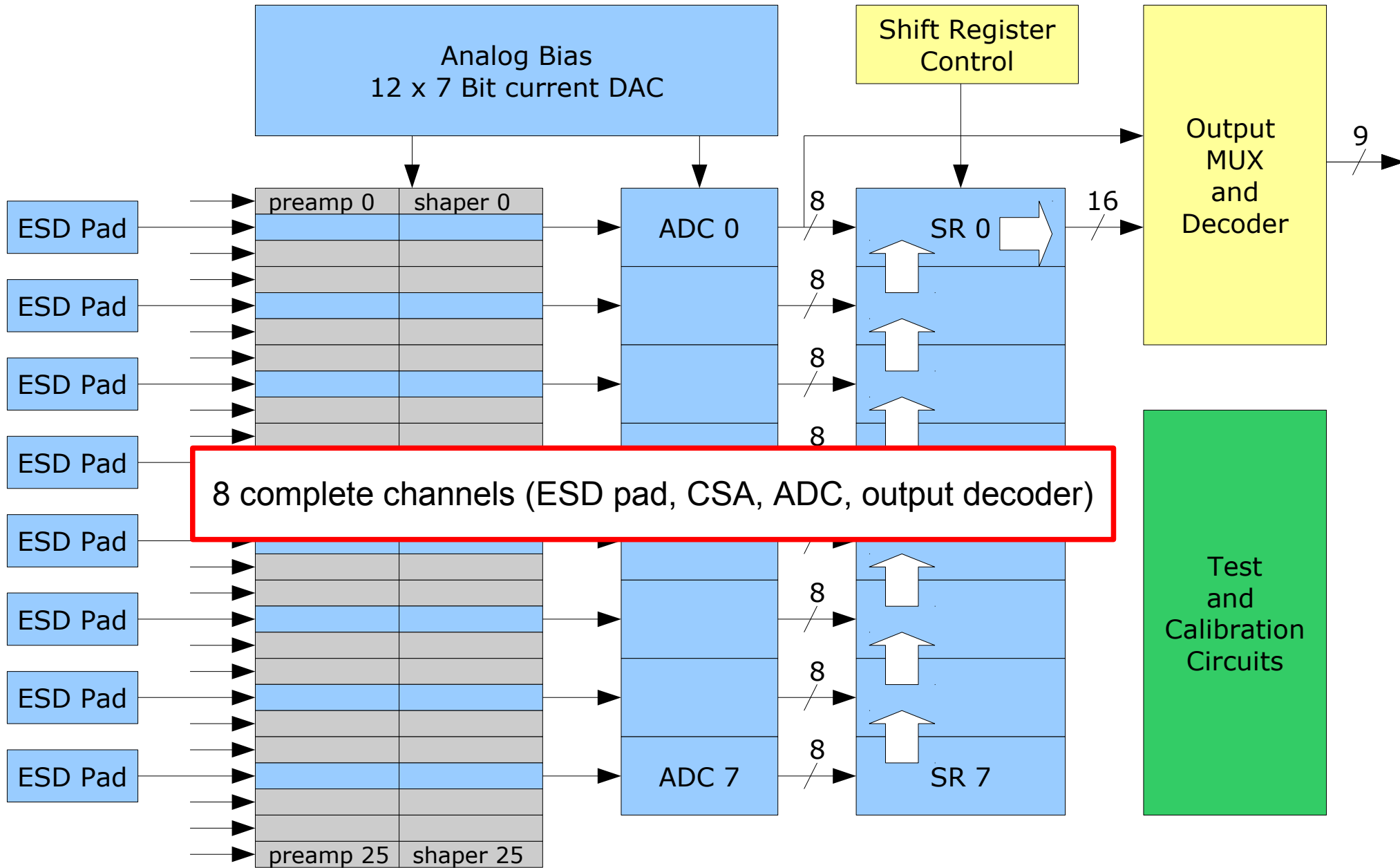
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FEE/DAQ Meeting @ FIAS (Frankfurt)

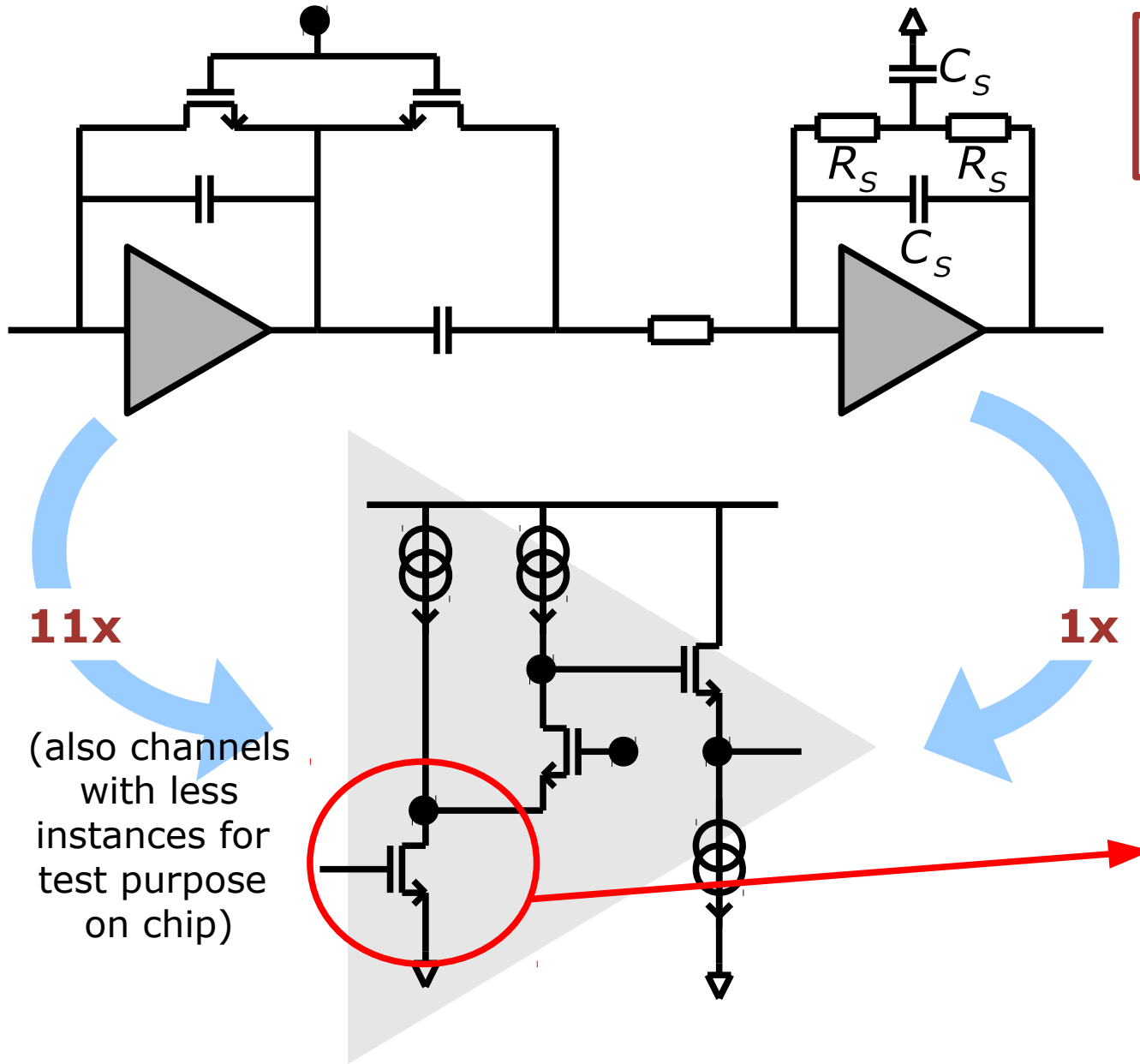
November 2010

1. Latest Chip Architecture (v0.3)

Block Diagram of Current ASIC



Reminder: Preamplifier/Shaper Circuit



$$H(s) \approx \frac{A_{DC}}{(1 + sR_S C_S)^2}$$

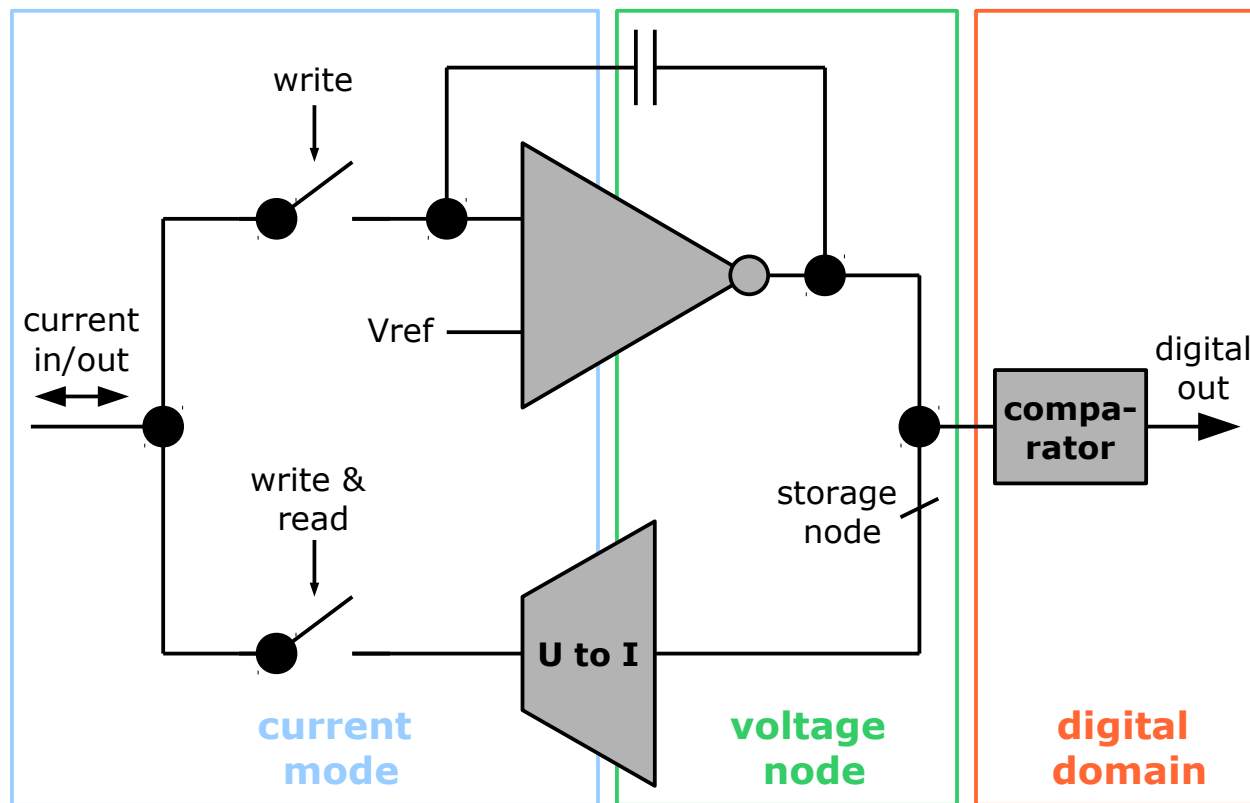
- O'Connor FB
- 2nd order shaper
- Shaping time: 82 ns
- Unified amplifier cell
- N-MOS input
- ≈ 3.6 mW/channel

New:

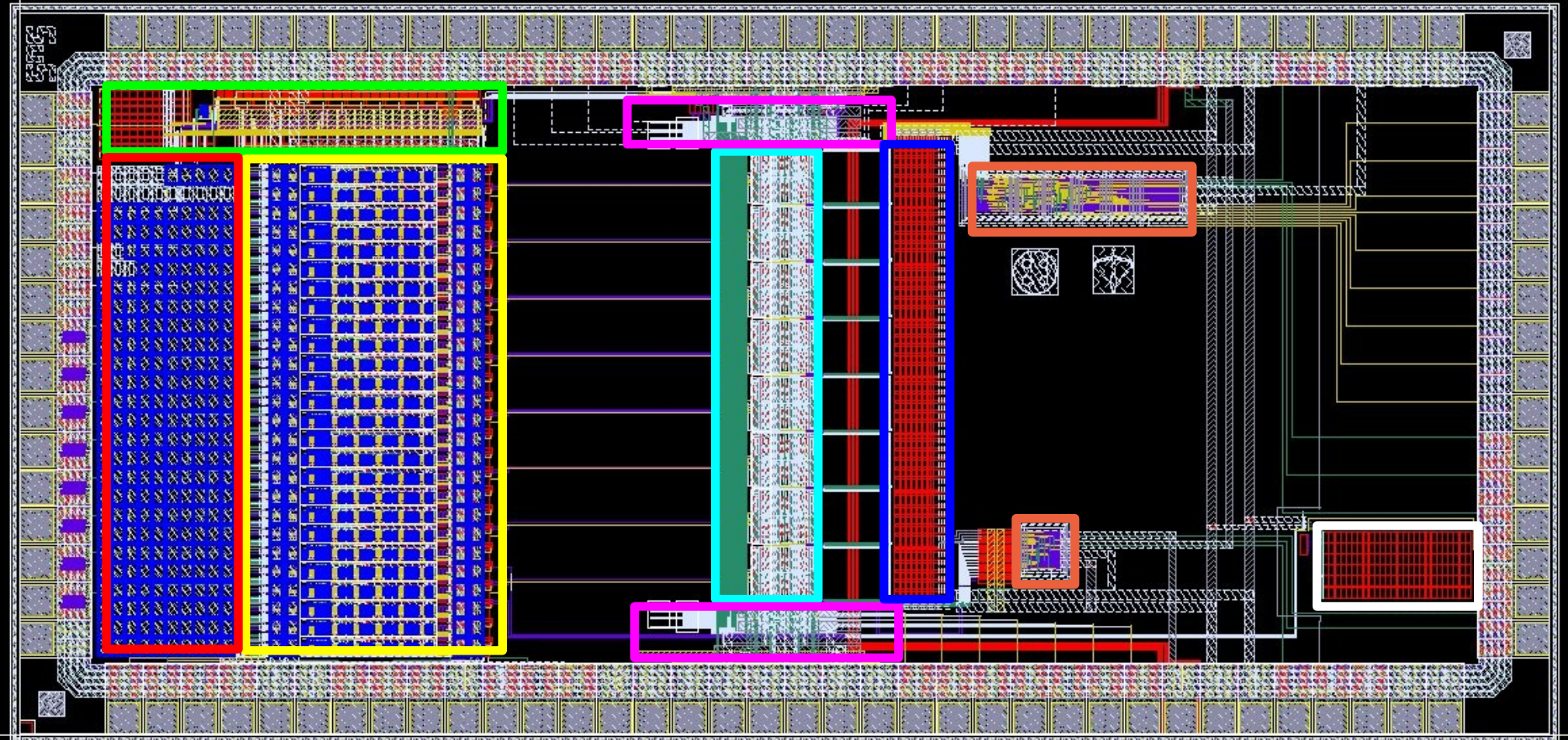
- Scaled lengths of input NMOS (180, 250, 320, 390, 460nm)
- Re-Layout of input NMOS: The (long) gate-fingers have been cut into smaller pieces to decrease gate resistance

Reminder: Algorithmic ADC Design

- 8 (scaled) pipeline stages, therefore 9 Bit design, **7.5 Bits effective** so far
- Algorithmic working principle ("1.5 redundant Bits" / conversion step)
- **25 MSamples/s, layout only 130x120 μm^2 , power consumption 4.5 mW**
- Core unit: Novel current storage cell:



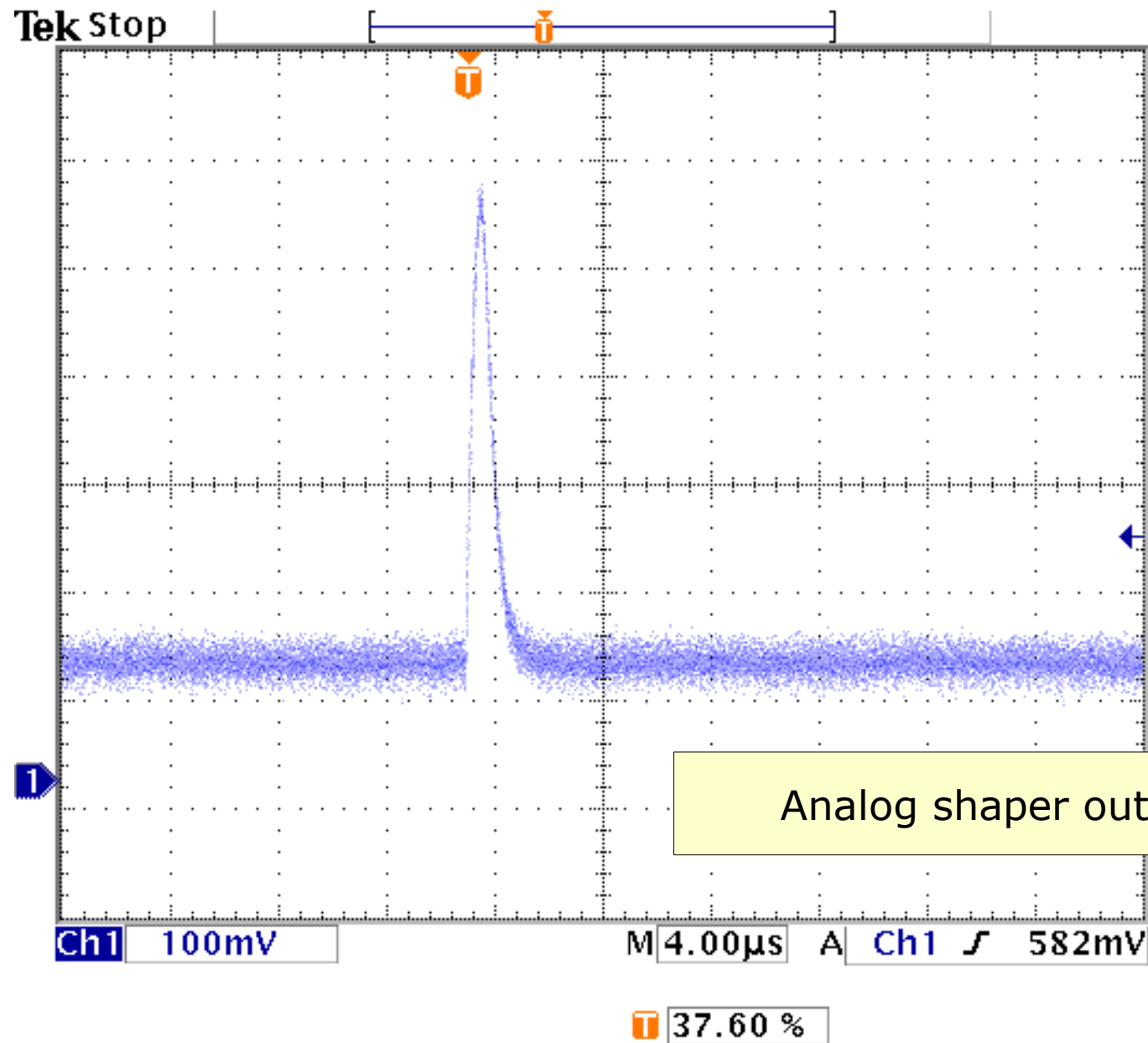
Current Test-Chip: Layout



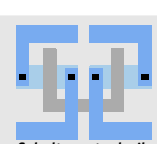
Bias circuitry (12 current DACs)
26 preamp/shaper channels
Detector capacitors (5pF per block)
8 pipelined ADCs

ADC control + bias
5.2 kBit shift register matrix
Control + readout/decoder logic blocks
Test circuits

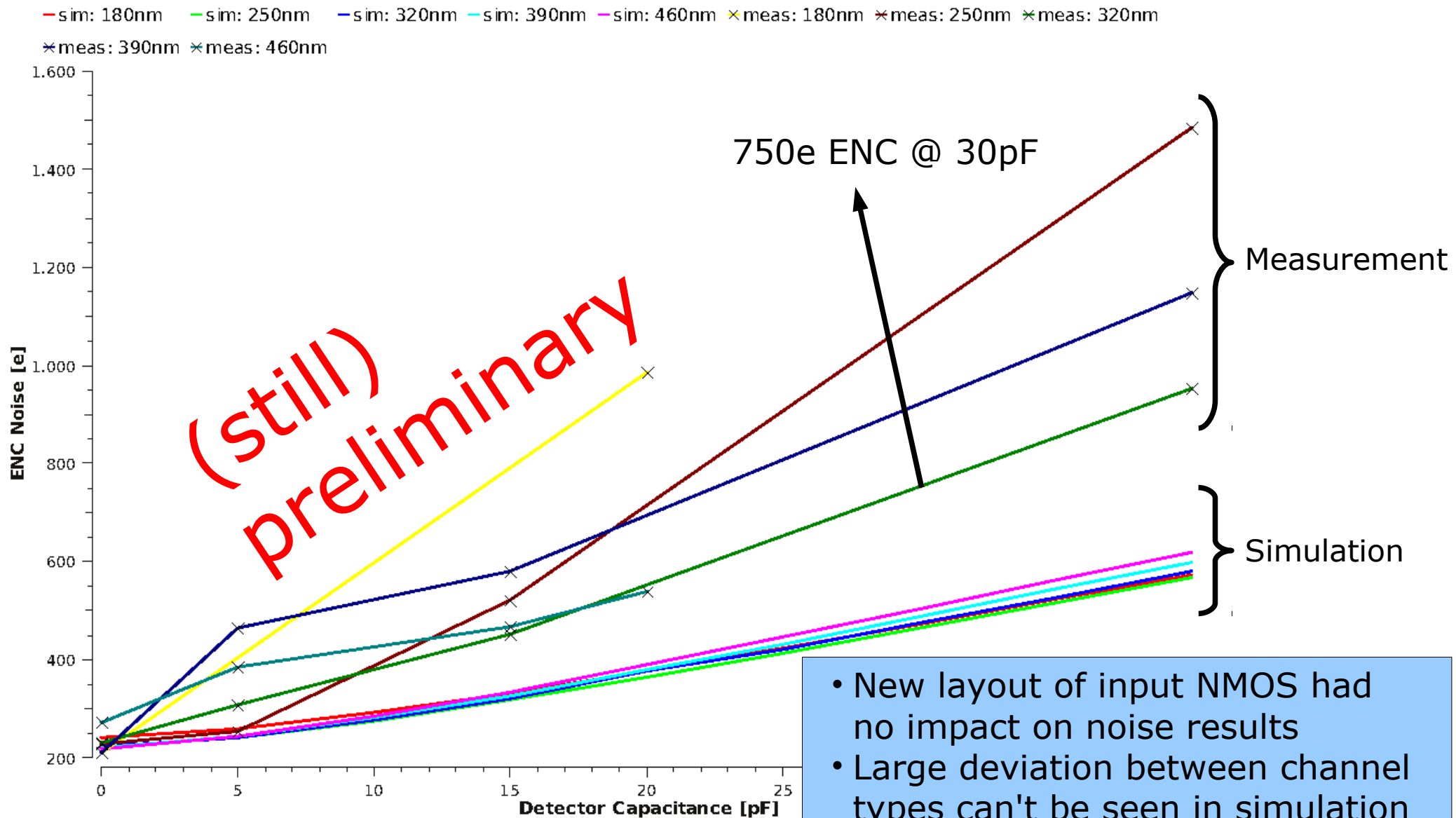
Typical Analog Shaper Pulse



7 Apr 2010
15:09:16

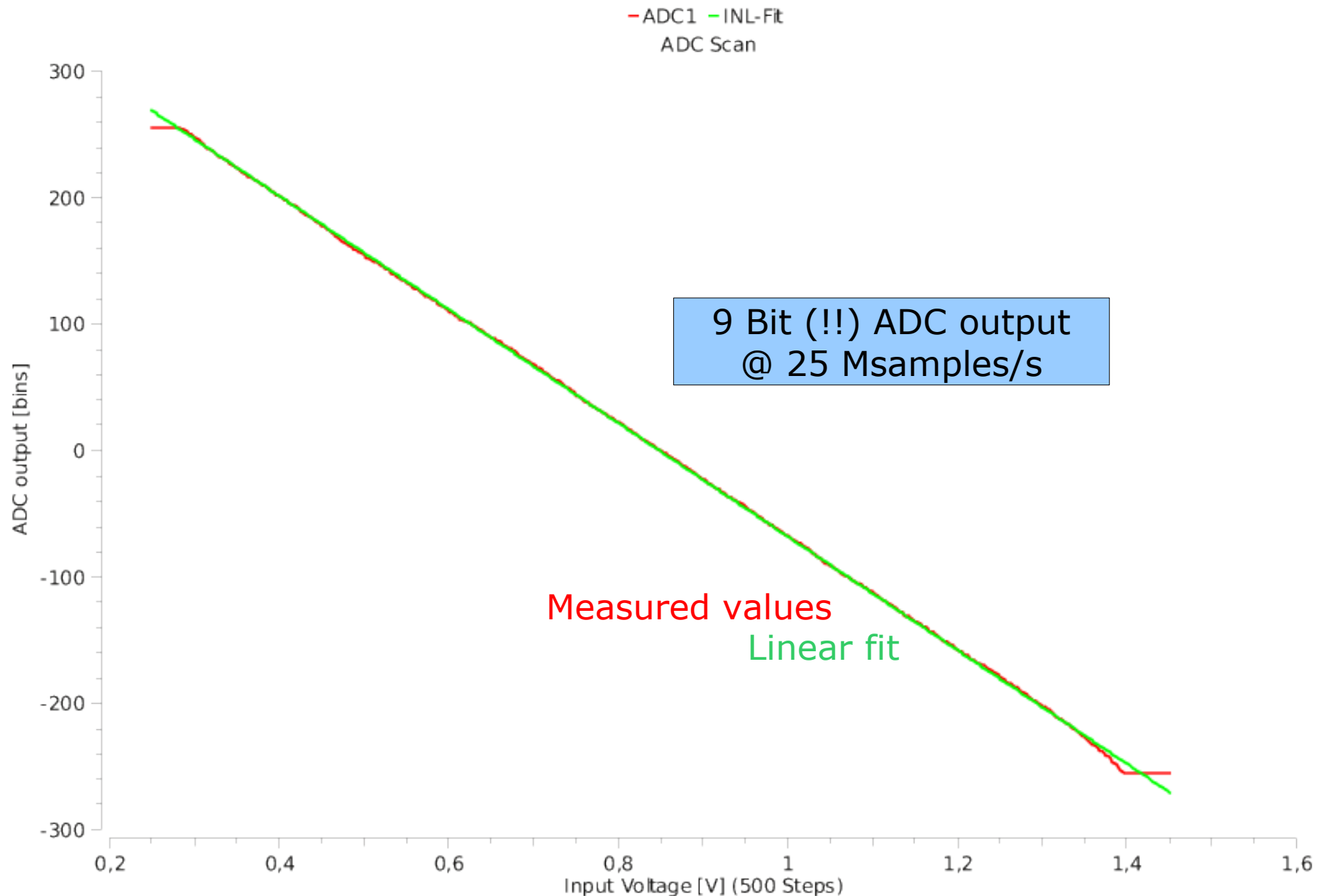


Preamp/Shaper Noise

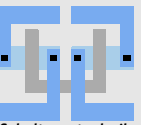
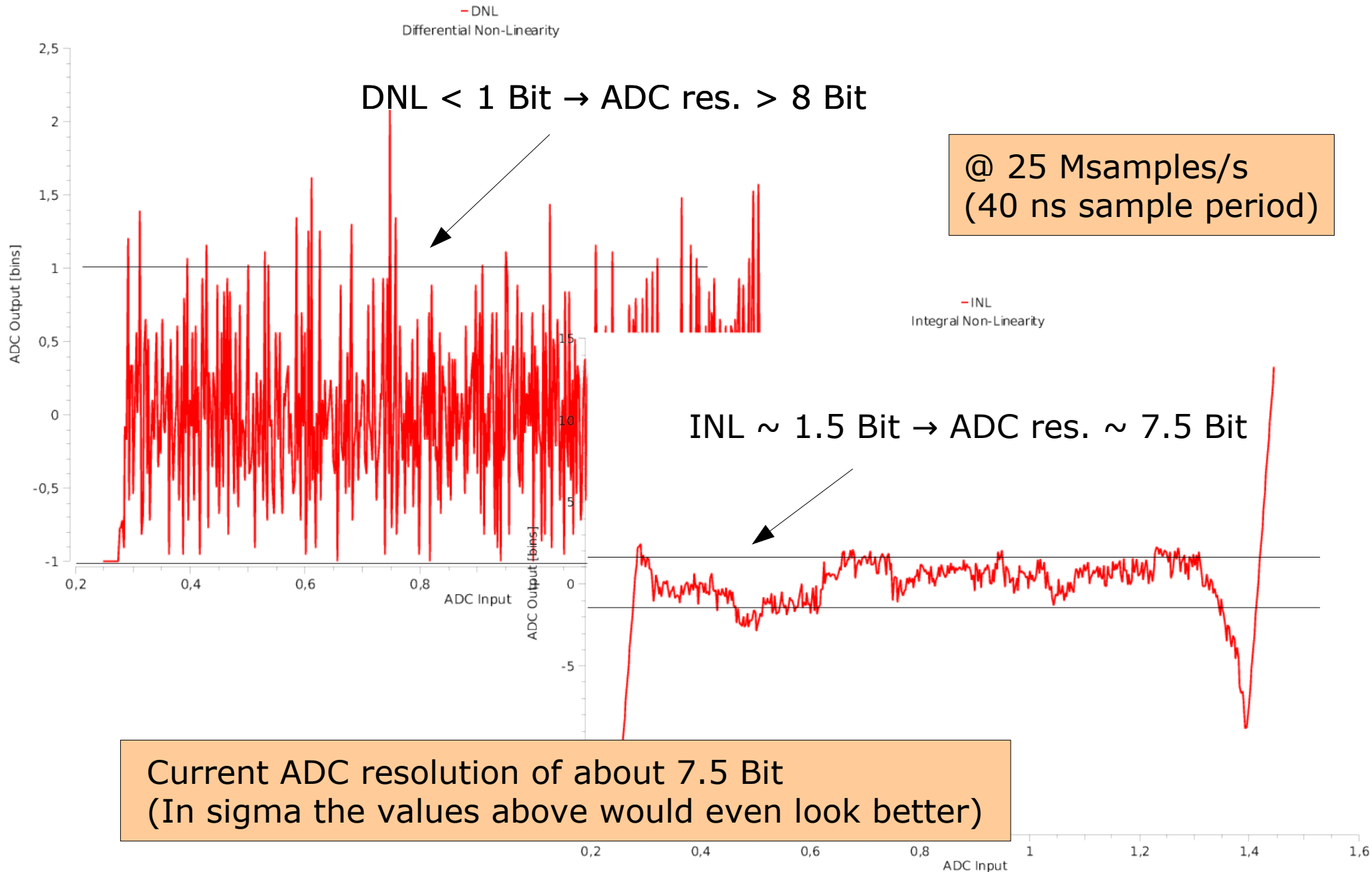


- New layout of input NMOS had no impact on noise results
- Large deviation between channel types can't be seen in simulation
- 320nm is the best choice

Characteristic ADC Curve

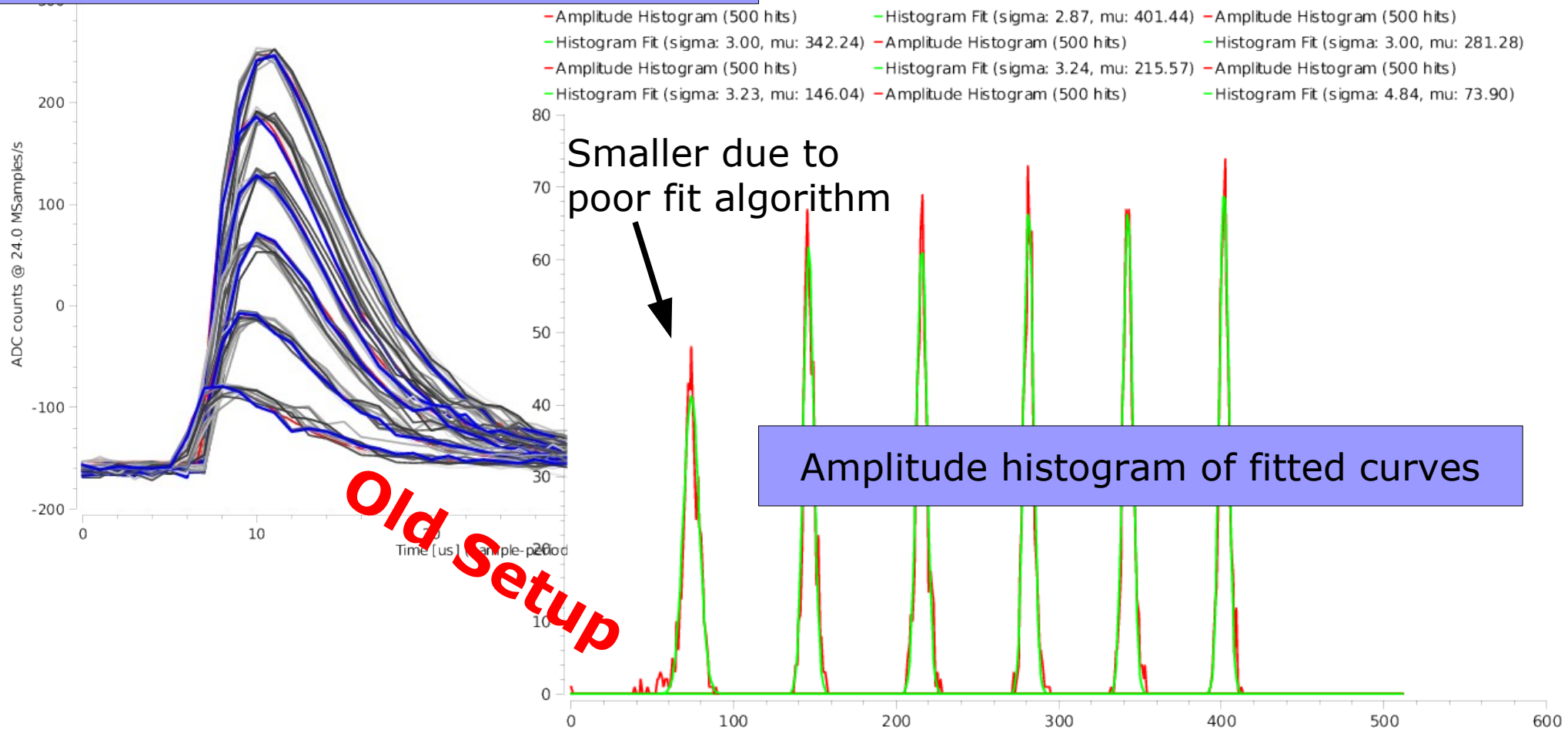


ADC's DNL and INL



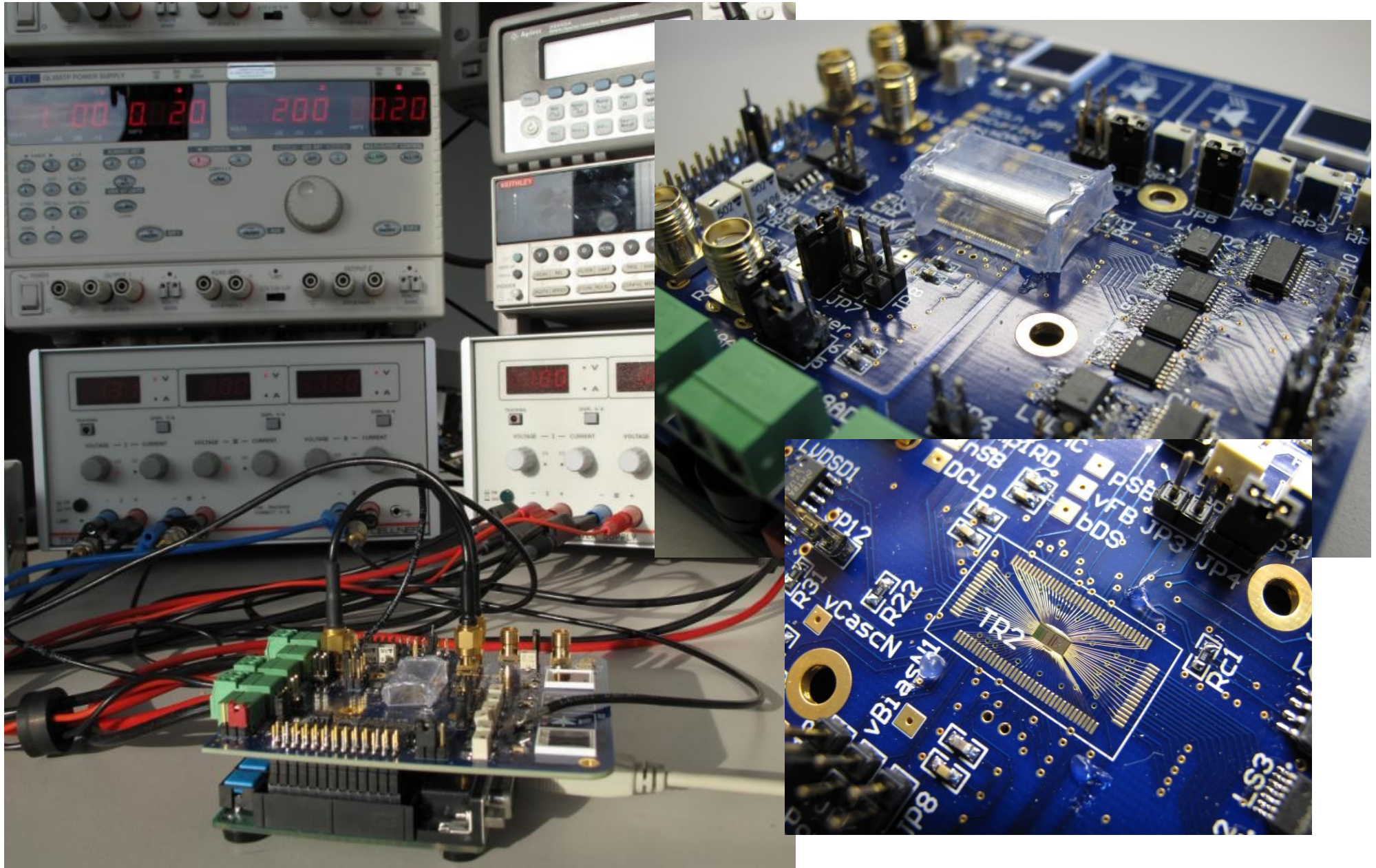
First (yet noisy) digitized pulses

Pulses for different input charges



Pulses with new setup look even much smoother (see next slides), but no measurement available yet :-)

(Old) Pre-Testbeam Setup

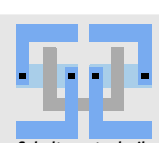


2. Testbeam Setup

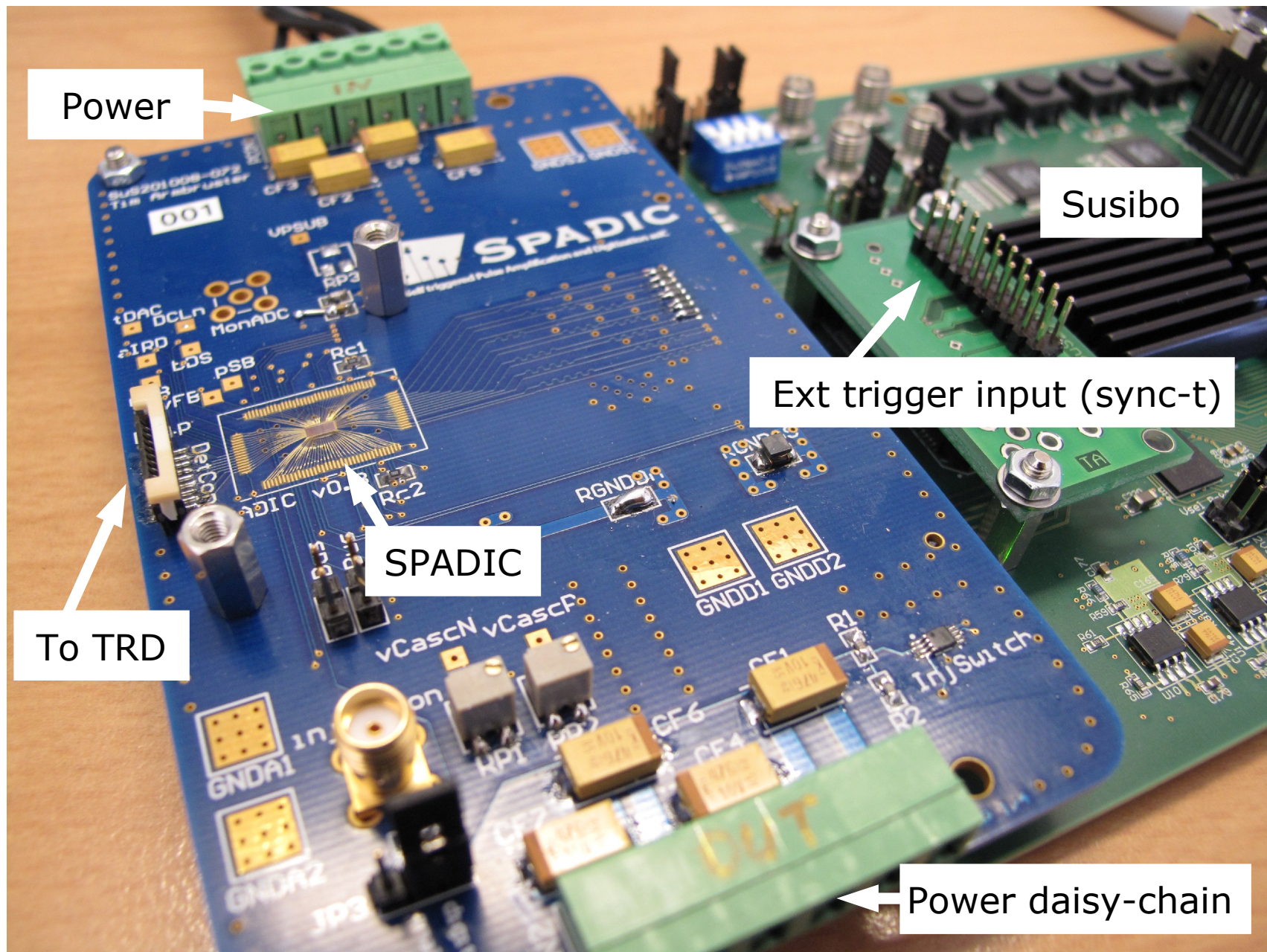
Testbeam Setup Overview

- “Old” chip (Spadic v0.3) but ...
 - New front-end PCB
 - Low-noise layout, several smaller improvements
 - Harwin ZIF connector compatible (same connector type as in ALICE TRD)
 - New FPGA readout controller (Susibo)
 - Virtex 5, 2MB SRAM, FTDI (USB 2.0), EEPROM(s), ...
 - New firmware
 - High readout rate of up to 8k events/s (368 Byte/event)
 - Package based protocol
 - New Features like local time-stamp, external event-id extraction (sync-t), ...
 - New Software-Library
 - Provides abstract functions like (dis-)connect(), readNextPackage(), status(), ...
 - Necessary for integration in DABC framework
 - New stand-alone readout client (hitclient)
- Beamtime target: 8 completely running Setups (8 channels each)
 - Last-minute point landing, also the Susibo was “just in time”
 - A lot of problems with assembly and bonding

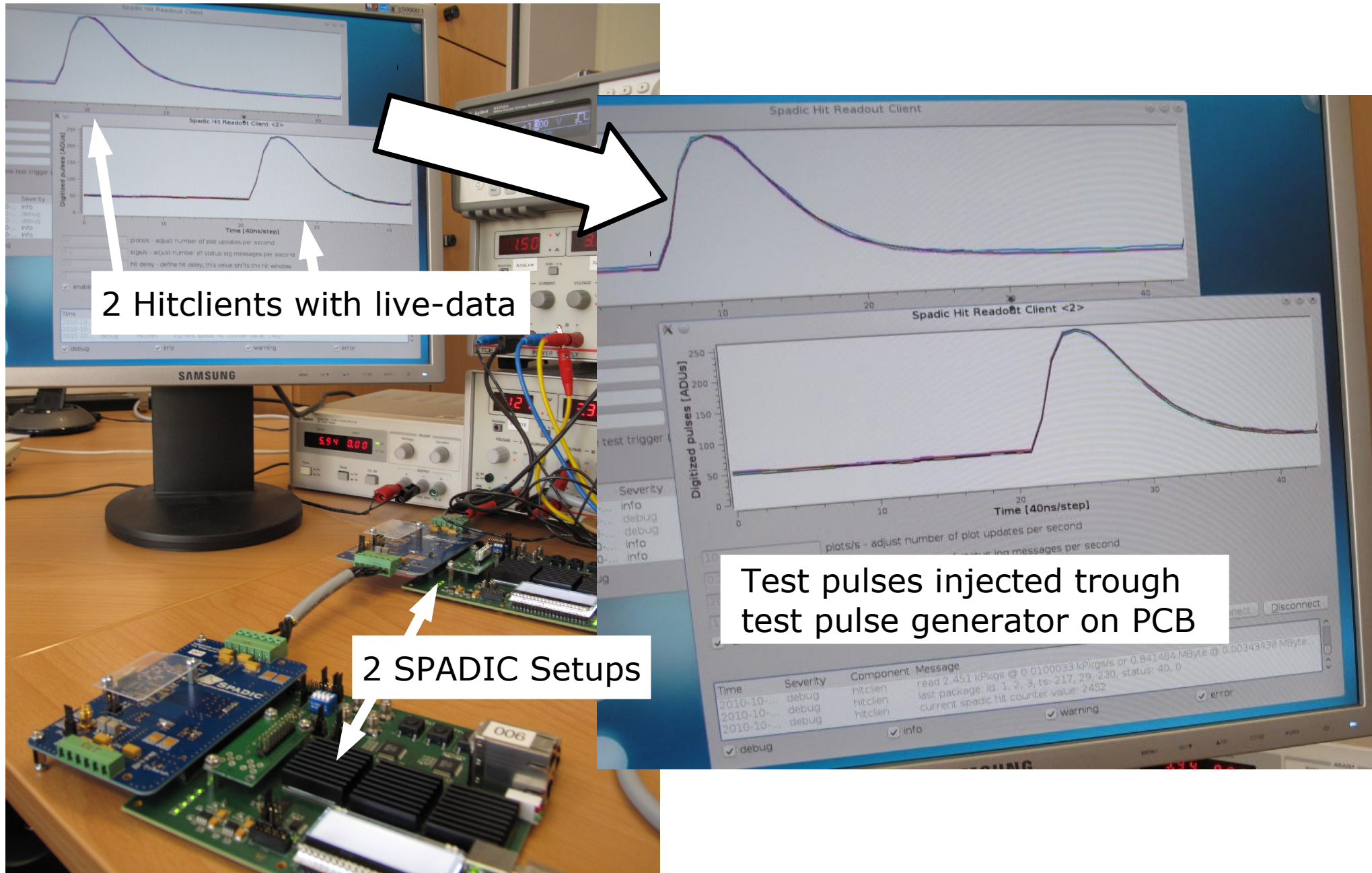
=> Finally 8 setups worked (most of the beam-time only 6 were run in parallel)



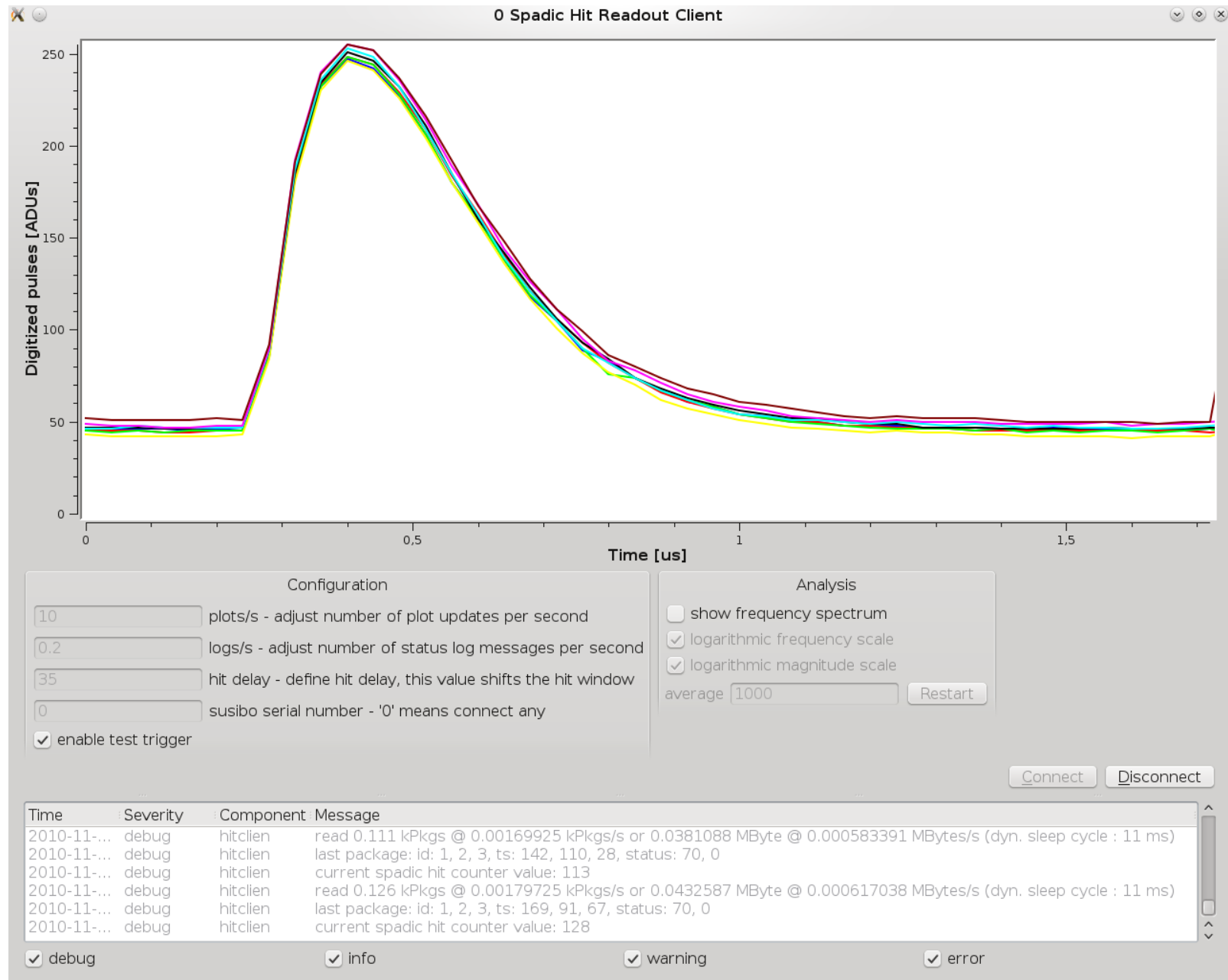
SPADIC plugged on Susibo



Setup in Lab

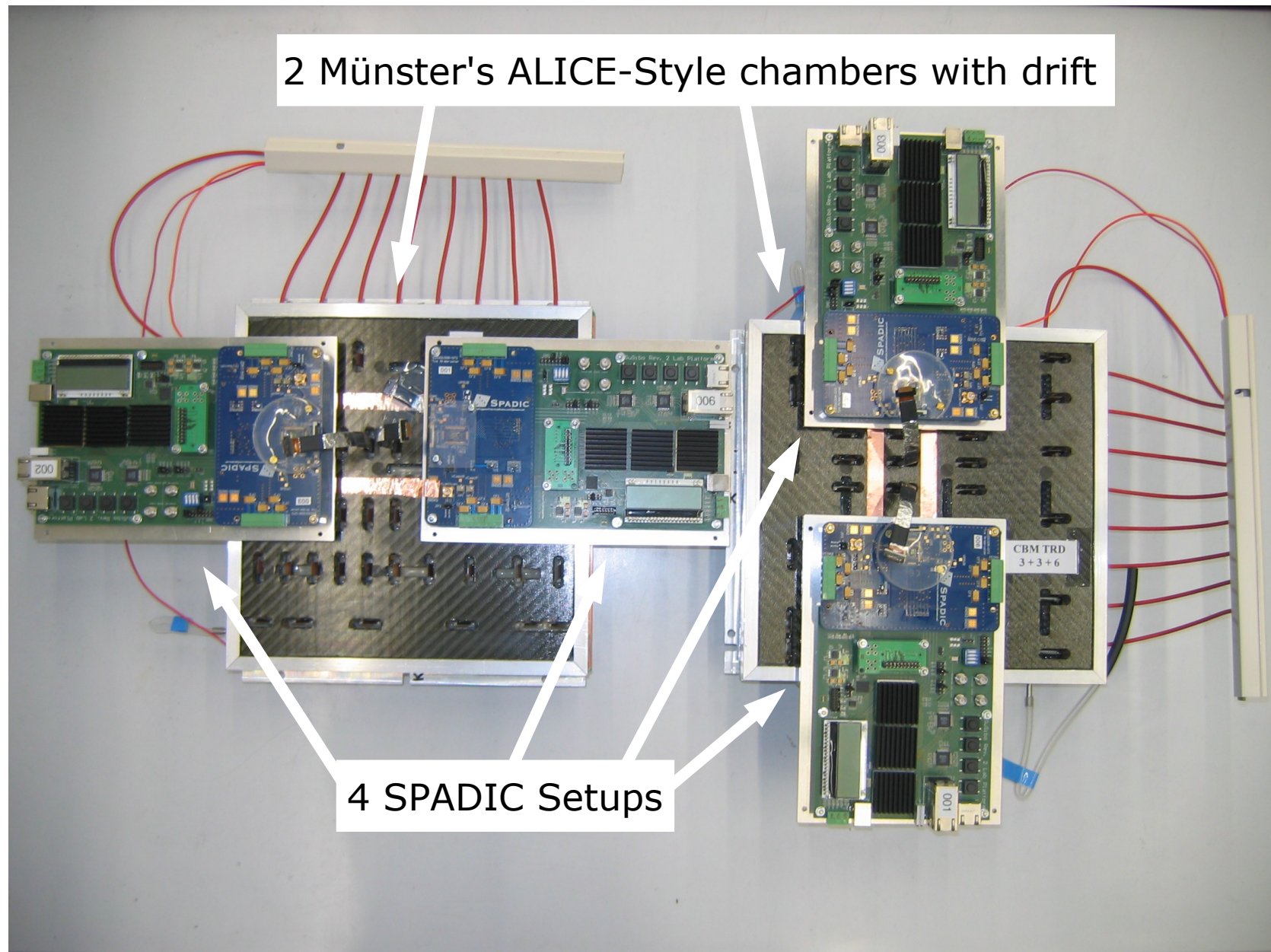


Hitclient Screenshot



Sorry, problem with my digi-cam :-(

Münster's TRD-SPADIC Setup

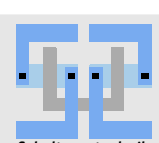


Sorry, problem with my digi-cam :-(

3. First Testbeam Results

Results from an electronic's point of view

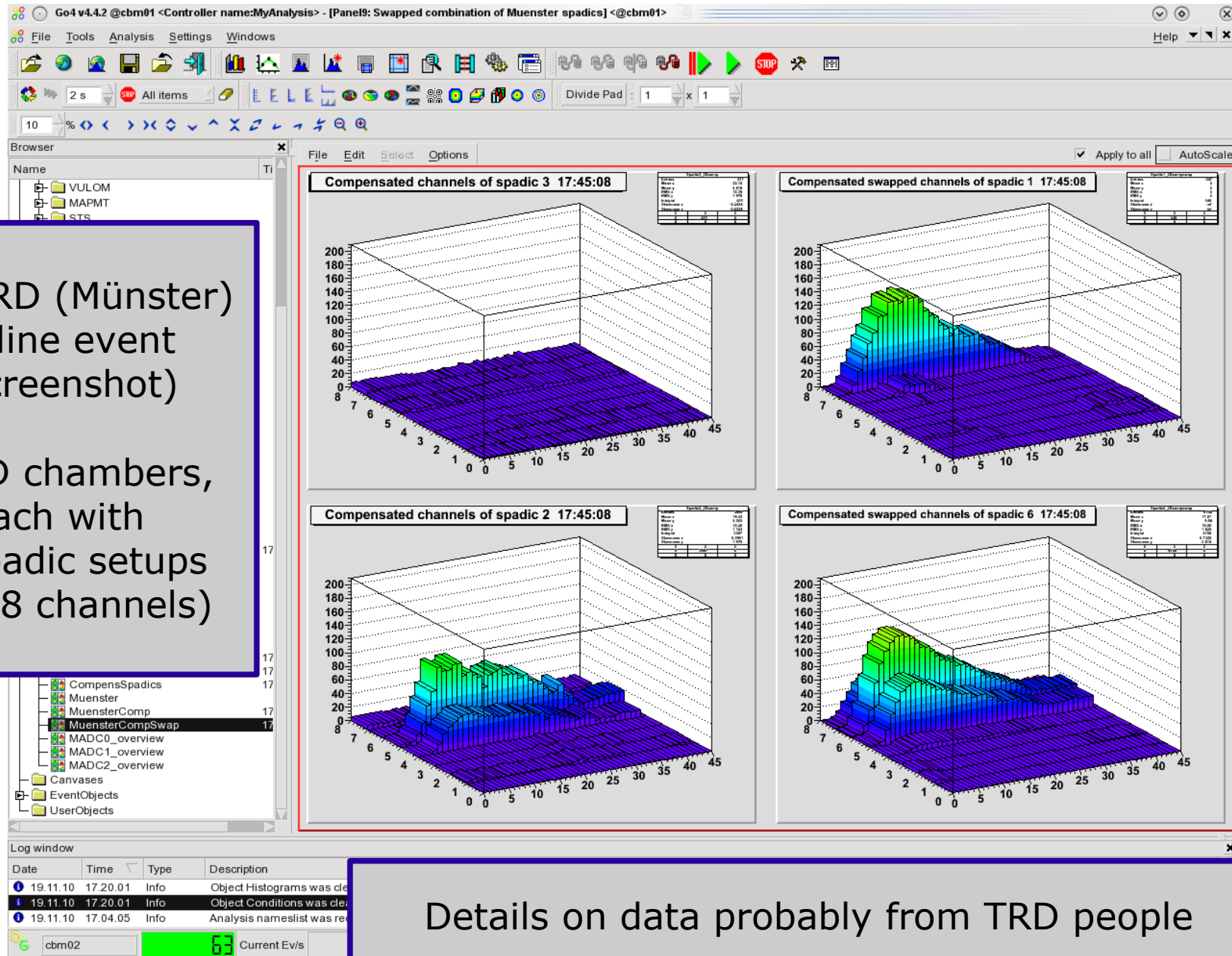
- Bad :-(
 - Many problems with pickup (external noise) – a lot of effort was necessary to reduce the different kinds of oscillation to a tolerable minimum
 - **Even after “optimization” some boards still showed strong oscillations**
 - (Due to known reasons) the chip's configuration was very unstable – a lot of re-configurations/restarts were necessary
 - Strange baseline-shift (DC-level) of shaper outputs if detectors were connected AND the ADCs were running (yet there was no time to investigate this)
- Good :-)
 - 8 Spadic/Susibo setups finished just in time
 - Successful integration of Spadic software library into DABC (thanks to Sergey and Jörn)
 - External triggering-scheme worked well
 - Finally 6 working Spadic setups in parallel (4 x Münster, 2x Frankfurt)
 - **A lot of nice hits could be recorded** (but also some ugly)



Go4 Spadic online event

Go4 TRD (Münster)
online event
(screenshot)

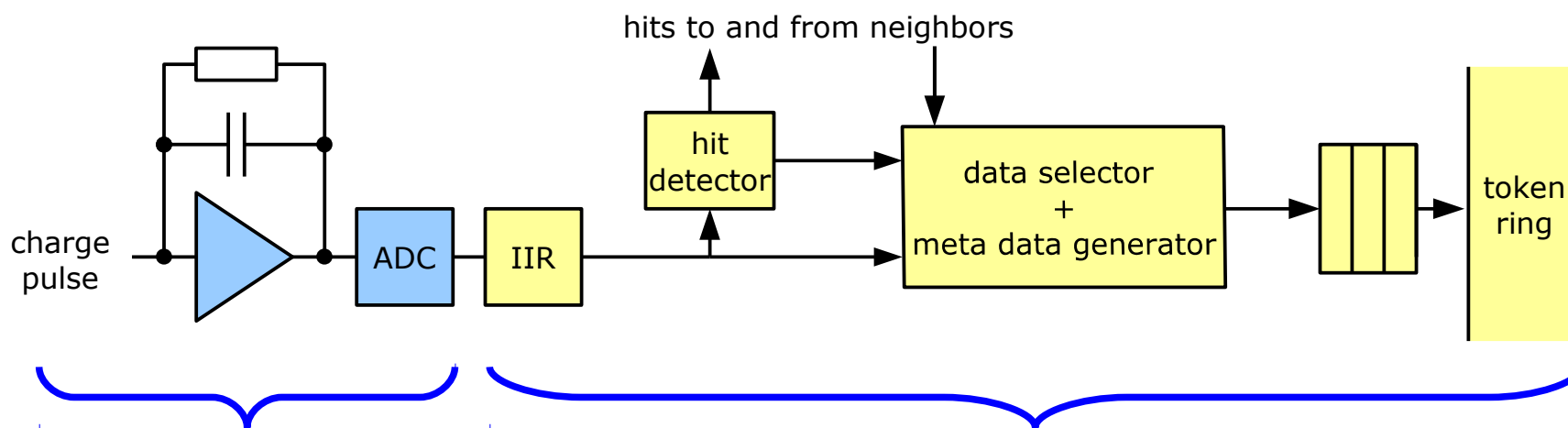
2 TRD chambers,
each with
2 Spadic setups
(2 x 8 channels)



Details on data probably from TRD people

4. Towards SPADIC v1.0

Status of Development



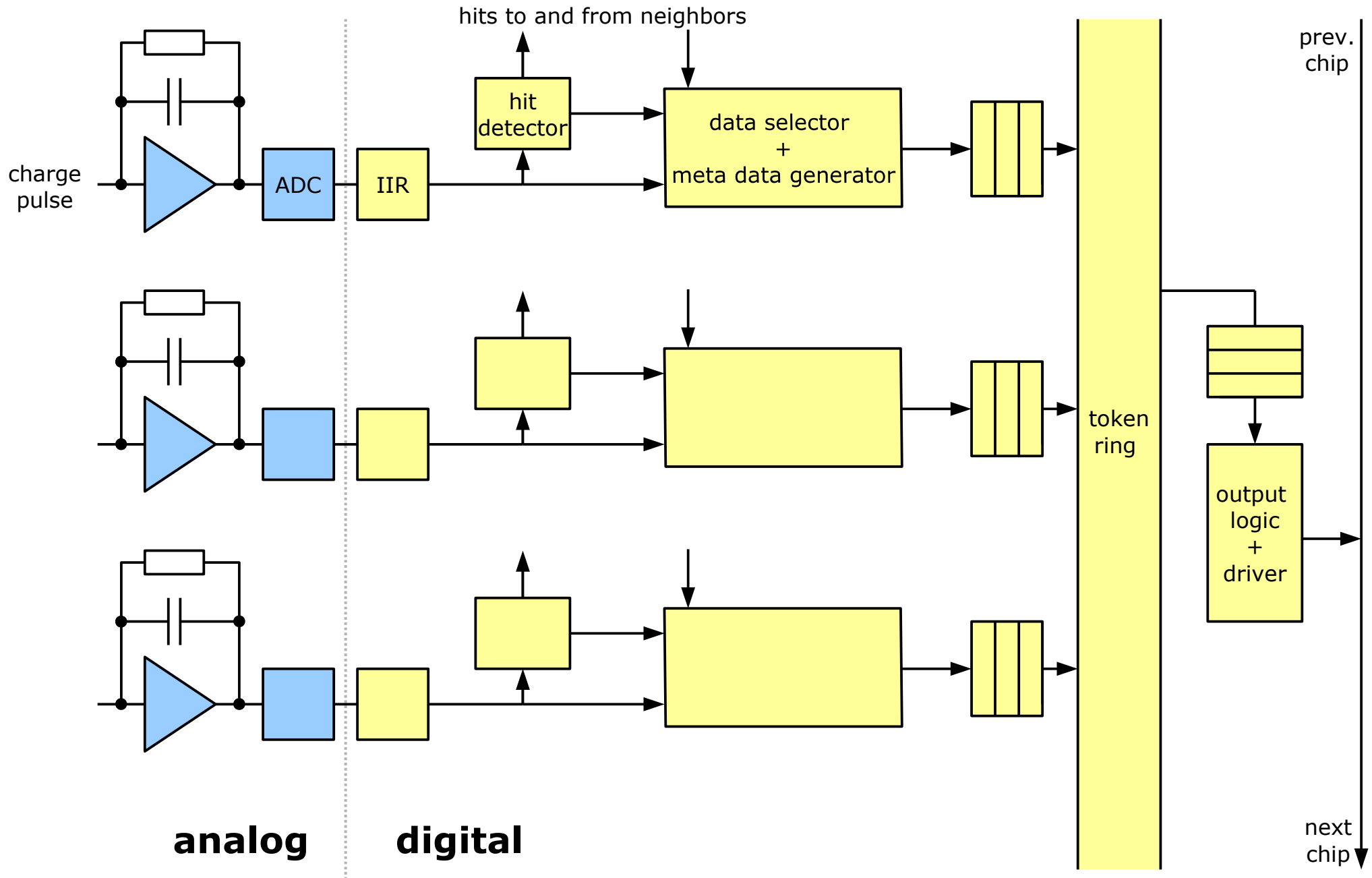
Analog Parts: Preamp, Shaper and ADC

- Several test-ASICs successfully designed and tested
- Working 8 channel readout setup (for testbeam as well as for chamber tests)
- Overall design concept mostly settled down
- A lot of parameters must be fixed soon

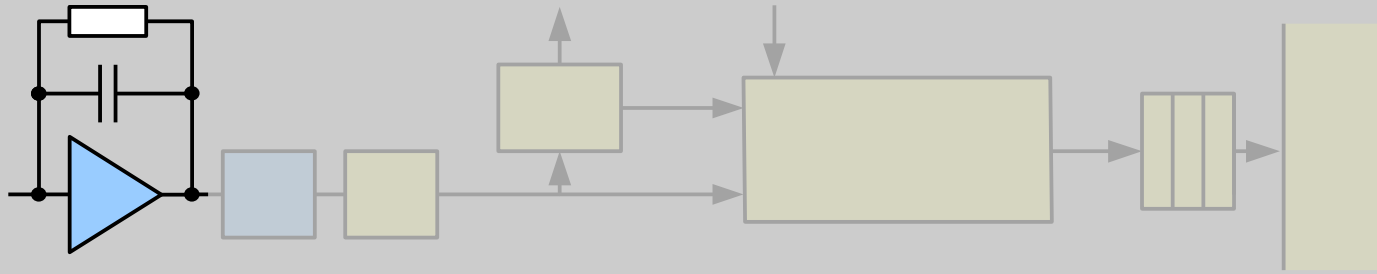
Digital Parts: IIR filter, hit detector, feature extraction (?), package generator, neighbor logic, token ring, interface protocol (Frank Lemke), ...

- First design proposal of data flow and control concept finished
- 1st Verilog iteration of most blocks available and simulated
- Michael Krieger, diploma student, working on IIR filter (ion-tail cancellation, ...)
- But: Still a lot of work to do ...

Conceptual Data Flow Diagram



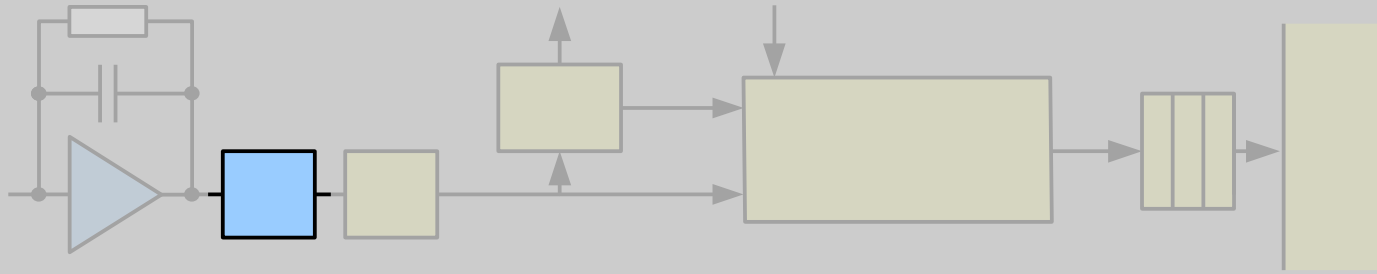
Spadic 1.0: Preamplifier / Shaper



- Charge sensitive preamplifier (CSA)
 - Single ended, N-MOS input
 - Input protection
 - Switchable polarity
 - Switchable # amplifier cells
- Shaper
 - 2nd order, PZ-cancellation, 82 ns
 - Switchable shaping-time
 - Increased order
- Both
 - 750e ENC @ 30 pF, 3.8 mW
 - Switchable gain

Already Available
Planned feature
Possible feature

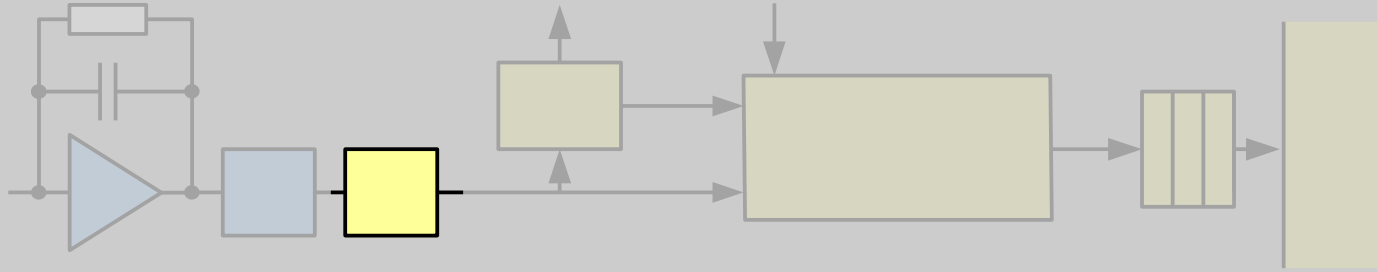
Spadic 1.0: ADC



- Pipeline ADC, continuously running
 - Current-mode algorithmic ADC
 - 9 Bit design, 7.5 Bit effective
 - Up to 25 Msamples/s
 - 4.5 mW / rad-tolerant
 - Slightly better resolution (~ 8 Bit)
 - High resolution (> 8 Bit), possible but very expensive in terms of man-power, power consumption, chip area, ...
 - Improved DC-Level / baseline adjustment mechanism

Already Available
Planned feature
Possible feature

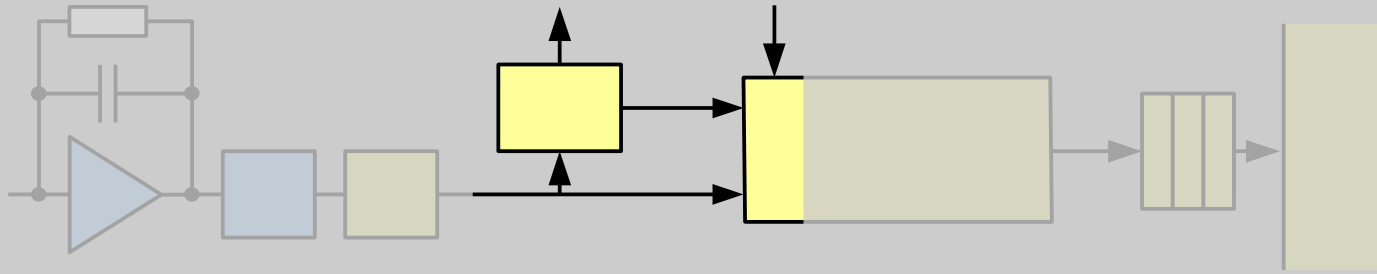
Spadic 1.0: Infinite Impulse Response Filter (IIR)



- IIR Filter / data pre-processing
 - Michael Krieger's diploma thesis
 - Simulation framework developed
 - 10-14 Bit multiplier + adder
 - Ion-tail cancellation
 - Baseline correction
 - Higher order shaping
 - (Simple) additional ideas ???

Already Available
Planned feature
Possible feature

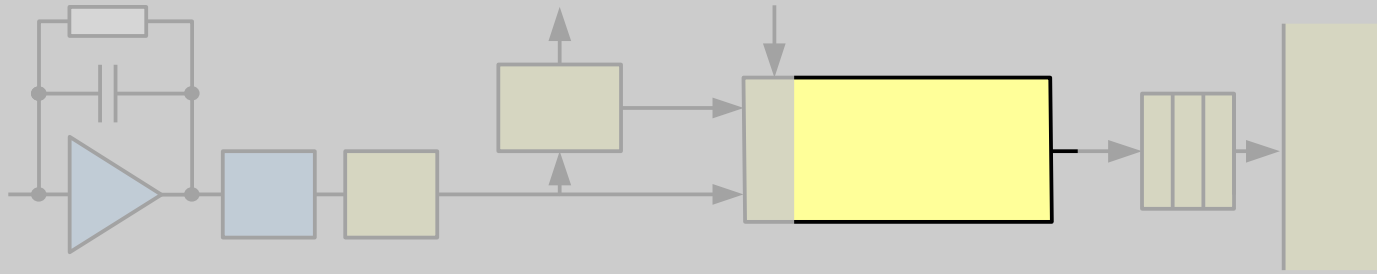
Spadic 1.0: Hit Detector and Neighbor Trigger



- Digital hit detector
 - Digital hit extraction logic
 - Different hit extraction schemes (threshold, double threshold, pulse length, ...)
 - 1th order Verilog, simulation works
- Neighbor readout logic
 - Automatic readout of neighbor channels
 - Trigger signal across chip edges
 - 1th order Verilog, simulation works

Already Available
Planned feature
Possible feature

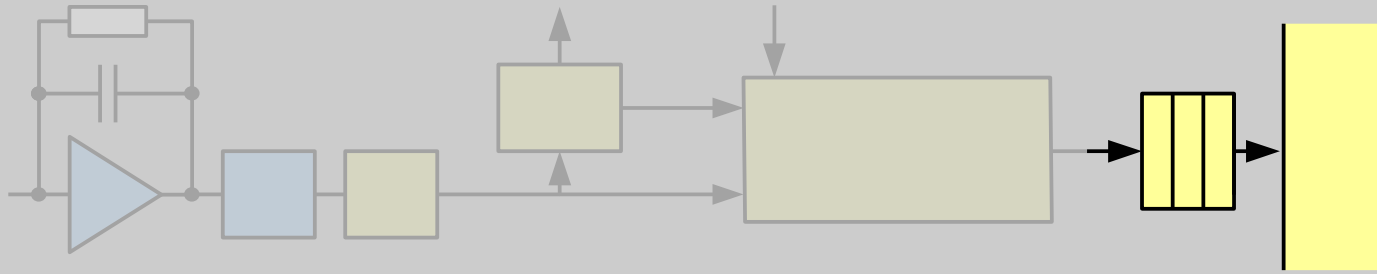
Spadic 1.0: Meta Data Generator and Package Builder



- Meta Data Generator
 - Local and external time-stamp extraction
 - Hit type extraction (internal, neighbor, ...)
 - Channel #, Chip ID, ...
 - 1th order Verilog, simulation works
- Package builder
 - Generation of hit package including meta and hit data
 - 1th order Verilog, simulation works

Already Available
Planned feature
Possible feature

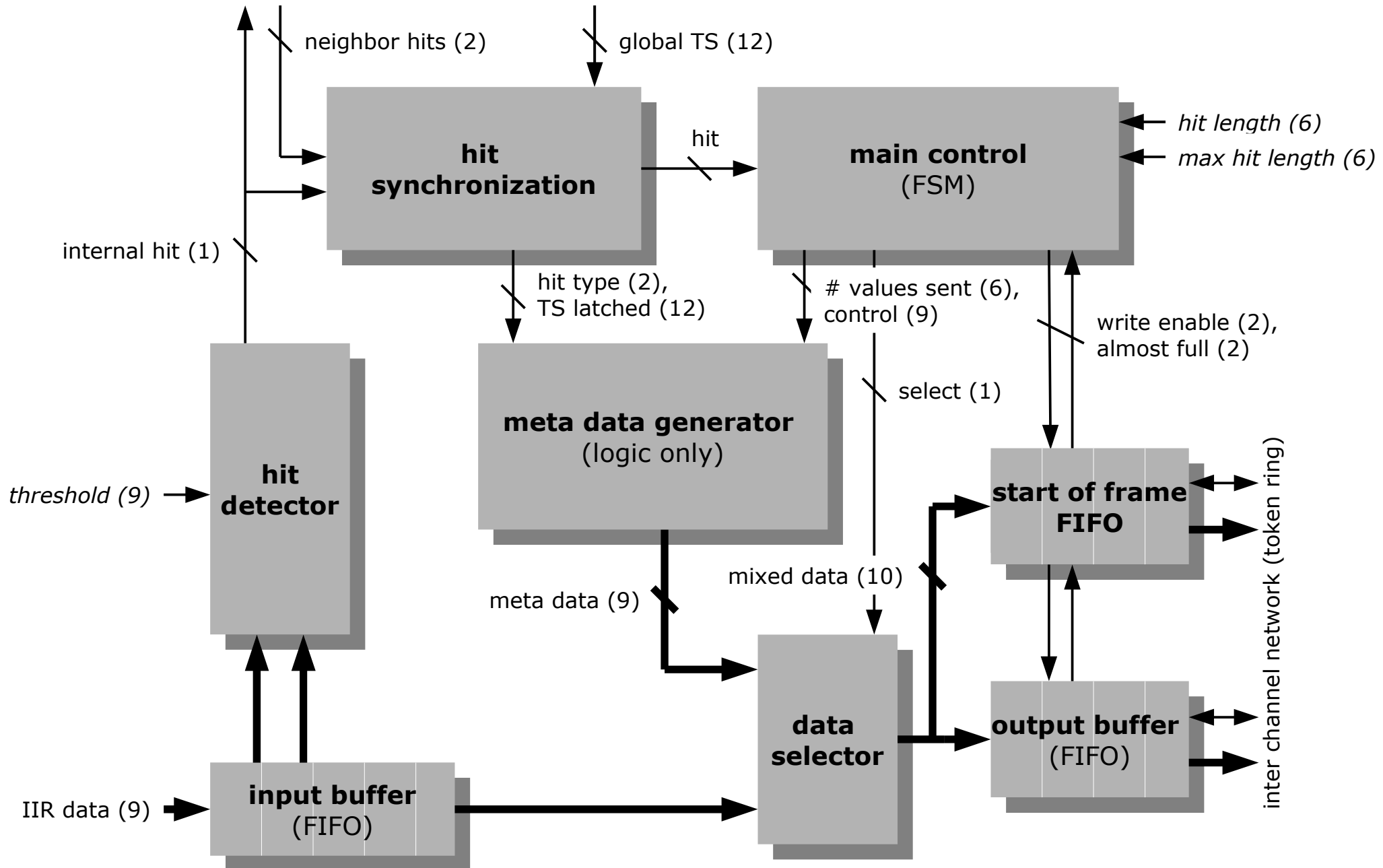
Spadic 1.0: Output Interface



- Output Interface
 - FIFO package buffer
 - Need access to some UMC 018 SRAM generator
 - Token ring inter-channel network
 - Sophisticated deterministic latency output protocol (Frank Lemke)
 - CBM DAQ compatible !!!
 - Serializer
 - Output driver

Already Available
Planned feature
Possible feature

Digital Hit Detector and Package Builder



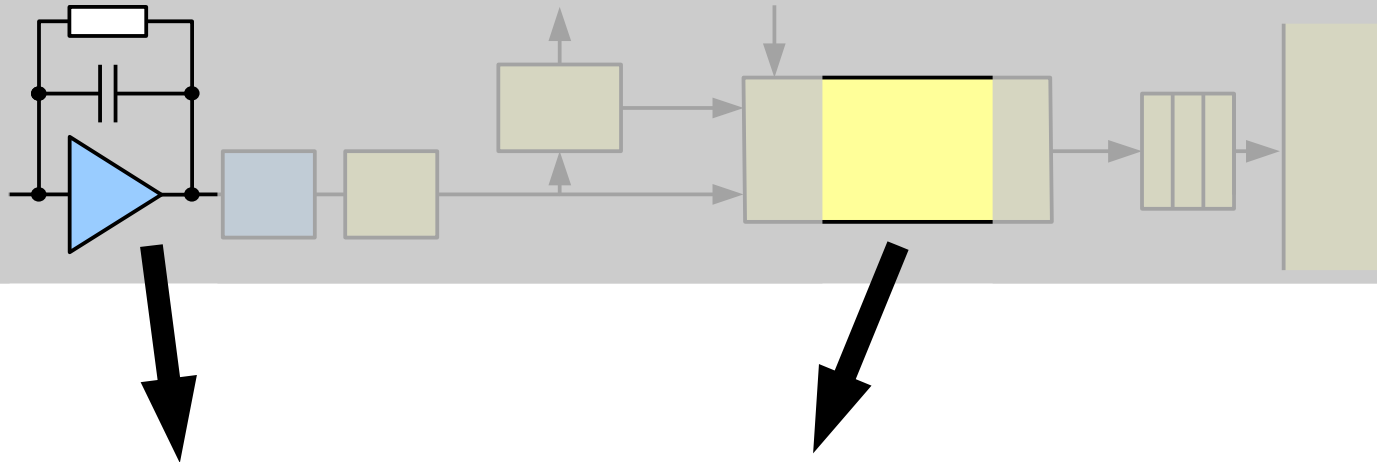
Chip Concept



Planned feature
Possible feature

- Features on chip-level
 - 32 channels / chip (maybe 64)
 - Several test mechanisms (test injection, analog signal access, ...)
 - On-chip bias circuitry (current DACs + diodes)
 - A lot of global and local configuration registers
 - Maskable channels
 - Power consumption / channel: analog $\sim 10\text{mW}$, digital ??? \rightarrow power limit?
 - Data: LVDS inputs / outputs only
 - Additional channel as global reference to eliminate systematic disturbances (e.g. pick-up)

If Spadic also goes for RICH people ...



- Necessary adjustments of Spadic 1.0 concept for RICH (Ring Imaging Cherenkov)
 - Much smaller input gain (max. 1.6 pC / hit) → switchable preamp/shaper gain
 - Negative input charge → bidirectional input stage
 - Very good time resolution $\sim 2\text{ns}$ → sophisticated feature extraction on-chip or offline
 - Is this time resolution achievable (40 ns sampling period)?
 - Energy feature extraction → on-chip (preferred) or offline (?)
 - Opt: more than 32 channels (≥ 64)
- **List not too long, but I'm already busy** → additional man-power on the horizon?

(Updated) Data-Rate Calculation

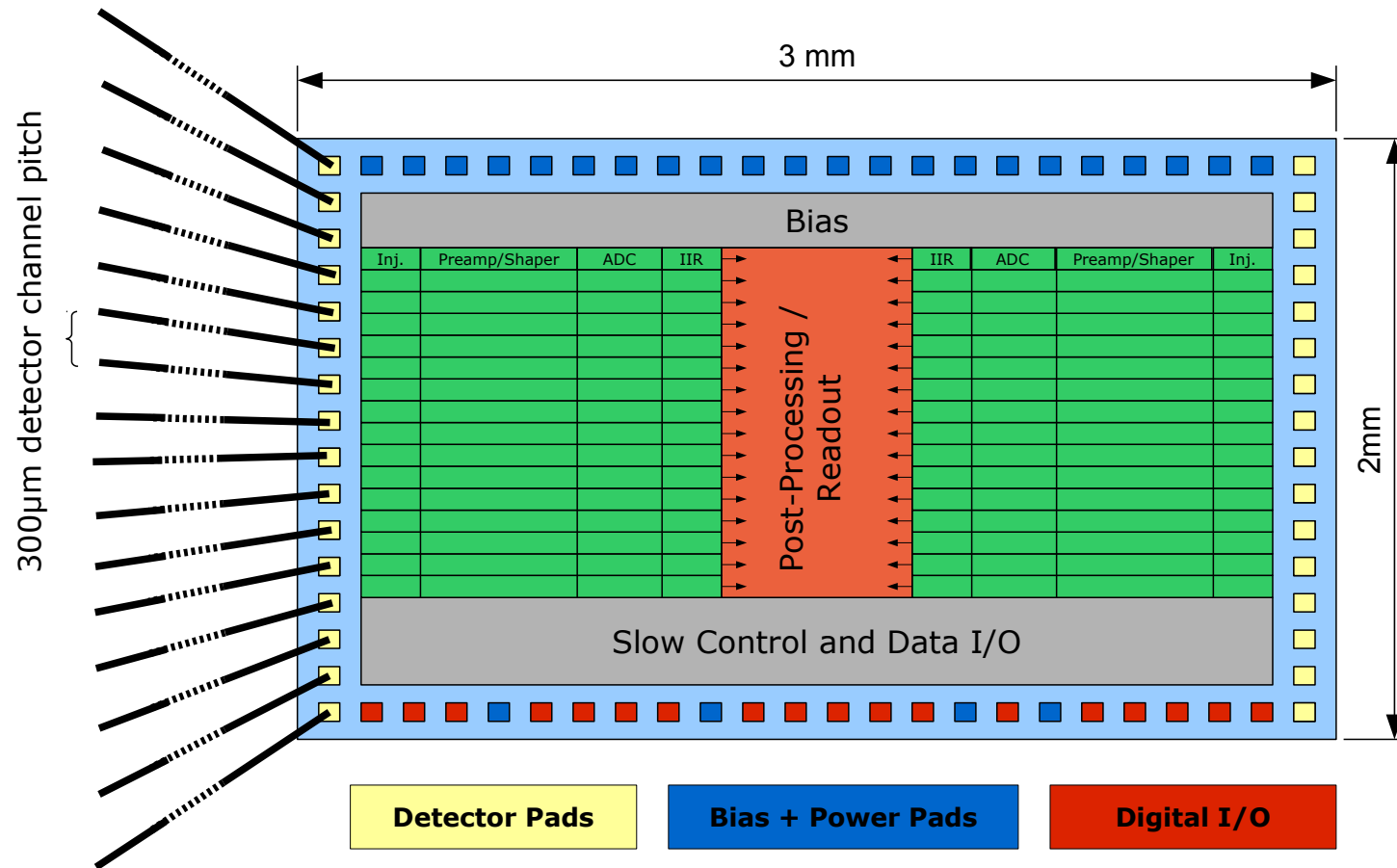
Some estimated numbers:

- 32 channels / chip
- 250 kHz maximum event rate / channel (one hit every 4 μ s)
- 8 Bit ADC resolution
- 10 samples / event **<= we need to further investigate here**
- 12 Bit time-stamp / event (epoch length 164 μ s @ 25MSamples/s ADC speed)
- 5 Bit channel ID

$$R_{chip} = \underbrace{\frac{250k \text{ events}}{\text{channel} \cdot s} \cdot 32 \text{ channels}}_{\text{hit rate chip}} \cdot \left(\underbrace{\frac{8 \text{ bit}}{\text{sample}} \cdot \frac{10 \text{ samples}}{\text{event}}}_{\text{hit data}} + \underbrace{\frac{17 \text{ bit}}{\text{event}}}_{\text{time-stamp+ID}} \right) = \frac{776 \text{ Mbit}}{s}$$

- => Conservative estimation: about 12 Bytes / (hit + channel)!
- => Planned output protocol from computer architecture group (Ulrich Brüning and Frank Lemke) foresees two links per chip with 500 Mbit/s each
- Note: Epoch counter + forward error correction overhead not considered here!

Floor Plan Proposal



- 3 x 2 mm² estimated die size
- 32 channels, 80 μm pitch, (mostly) symmetric layout for low(er) IR-drops
- Detector connection-pads on two sides (chips will probably be attached to back of detector-module, this relaxes routing/spacing)

5. Future of the Test-Beam-Setup

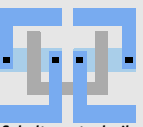
Spadic User Community

- (Potential) users of the “Spadic Test-Beam” setup
 - **IKF, Frankfurt** – currently making first steps (2 boards)
 - **Uni Münster** – currently making first steps (2 boards)
 - **JINR Dubna** – showed interest in using the setup for their chambers
 - **RICH, GSI** – readout of the photomultipliers with Spadic just as a proof of principle and to get familiar with the setup (usage of course not as a working horse)
- Other planned “Spadic Test-Beam” setup activities
 - Readout of some strip diodes from Johann (GSI) as a proof of principle and to measure some spectra
 - GSI would like to gather bonding-experience with some Spadic chips

=> To a certain limit, **I would like to improve the current setup** and ...

- ... add some additional features (e.g. include a sync-t trigger generator)
- ... stabilize the readout
- ... re-iterate the front-end PCB (remove some little bugs, optimize the detector connectivity, consider some external advice, add footprint for strip diode, ...)

But all this strongly depends on available man-power and willingness to cooperate!



6. Next steps and timetable

Next Step: Iterate over Specification

- I've started a Spadic 1.0 specification file
- Everybody concerned should help interating it
- We need to fix all basic numbers before the chip development starts

spadic10spec.pdf - Adobe Reader

Datei Bearbeiten Anzeige Dokument Werkzeuge Fenster Hilfe

spadic10spec.pdf x

1 / 3 75% Suchen

Spadic 1.0 Specification

Tim Armbruster
November 24, 2010

1 Physics requirements

	TRD	RICH
channels / chip	32	opt. 64 (32 ok)
channels / system		860x64=55040
chips / system		
power limit / channel		threshold dispersion
noise limit		
maximum radiation dose		
maximum input capacity		maximum HS 10
average input capacity		
average event rate		
average hit rate per channel		
maximum hit rate per channel		200 kHz
maximum leakage current		none
average charge per hit		10 ⁶ e
maximum charge per hit		5-10 10 ⁶ e
type of energy distribution	exp.	Gauss
measured quality	spatial res.	binary readout
input signal		pulse (j 10 ns)
required Energy resolution		8 Bit
required time resolution		target 2 ns (5 ns max.) sigma
special tasks	baseline rec., ion-tail can.	feature extraction (time, energy)

2 Data sheet

2.1 Spadic 1.0 data sheet

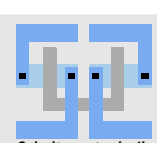
Parameter	Value	Comment
Technology	UMC 180 nm	
Number of channels	32	
Chip size		
Number of pads		
Total power consumption		
Total dynamic range		

Under Construction

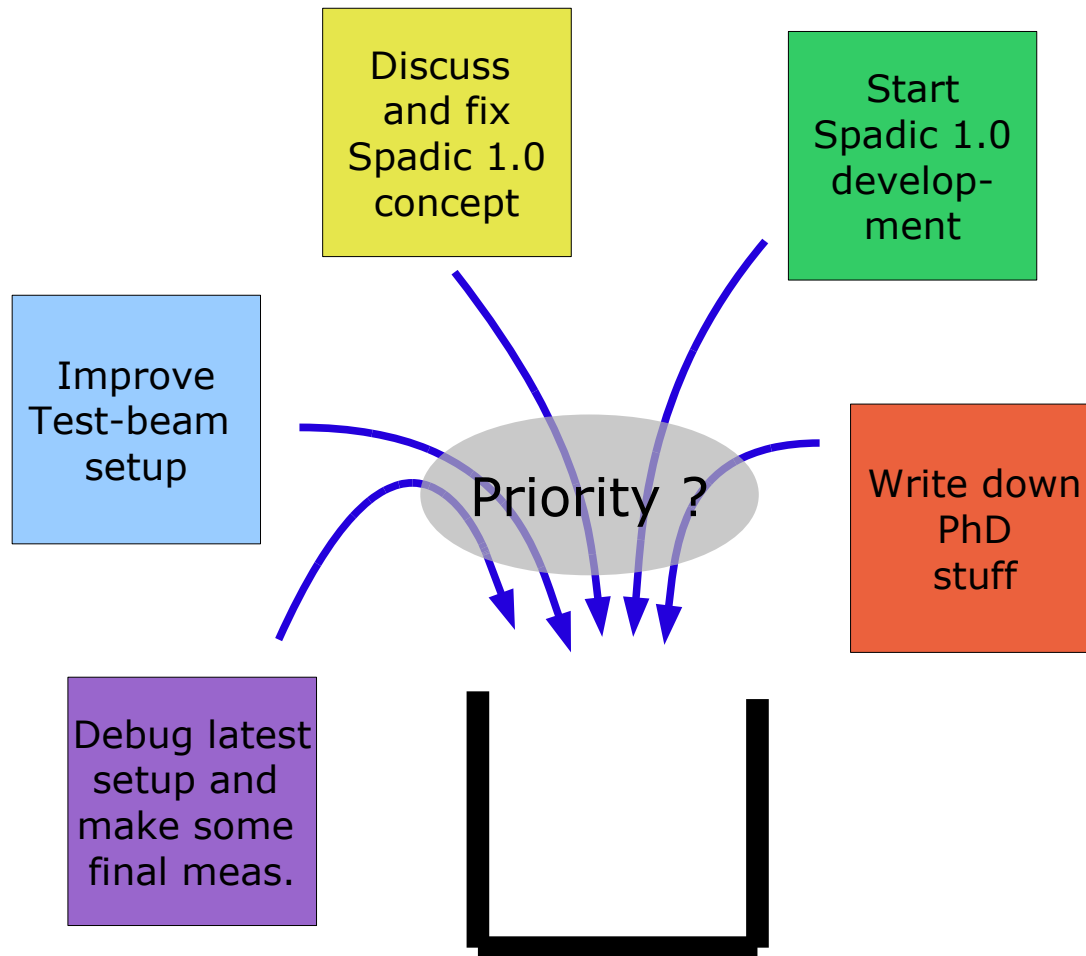
Next Step: Debug and improve Testbeam-Setup

- We still need to understand ...
 - ... the strange baseline shift ...
 - ... the high sensitivity to pick-up noise (PCB, chip or detector problem?) ...
- We probably should gather some more experience by ...
 - ... reading out some silicon strip detector ...
 - ... (maybe) reading out the RICH photodiodes ...
 - ... further improving the setup (see need to understand) ...

... **before** we finish the Spadic 1.0 development.



Timetable



- A lot of different tasks
- I need to decide when to start writing down my PhD (plan was to start at beginning of 2011)
- A **very** optimistic estimation for the submission of Spadic 1.0 is middle of 2011
- A priority list, working packages and a timetable must soon be defined
- **The focus should go as soon as possible to the Spadic 1.0 development!**

5. Summary and Outlook

Status of the latest setup:

- 8 working Spadic v0.3 / Susibo setups
- Successful integration in CBM test-beam environment
- Promising results in lab and from test-beam but also open problems
- A lot of interest in using the current setup from different groups

Status of Spadic 1.0 design concept

- Complete design concept available
- Analog part (except for some improvements) conceptually completed
- Most digital building blocks still in a very early design phase
- Many features still need to be discussed
- Design kick-off as early as possible in 2011

Next Steps:

- Improve latest setup and gather more experience with chambers and silicon
- Discuss and fix specification
- **Focus on Spadic 1.0 development**

